

## Mission Statement

"The **INTERTECH** conference will serve as an international forum on new technology for diamond, cubic boron nitride (cBN) and other related materials classified as superabrasive or ultra-hard materials. **INTERTECH** will educate attendees and disseminate research and application development information covering these materials. **INTERTECH** will host all global manufacturing, technical, research, academic, commercial and end user organizations to share scientific breakthroughs and innovations. **INTERTECH** will adhere to the mission of blending technical innovation, research and product development with the ultimate focus on end user application."

## Key Conference Features

- A unique occasion to interact with technical and business leaders within the structure of a Global Technical Conference.
- Reception to meet other attendees, presenters and business leaders.
- Opportunity to hear experts from diverse technologies and to personally interact with all presenters and attendees.
- Tabletop displays and exhibitions from leading companies in the industry with time to discuss products and solutions.
- Technical and application presentations from all areas of interest to evaluate growth opportunities of diamond, cBN and other ultra-hard materials with a focus on performance and productivity.
- Newly formed Educational Session for users, engineers, sales, marketing and all others wanting to learn about the superabrasives industry, products and applications.
- Chance to evaluate emerging technologies and materials for your own application situations.
- Outstanding venue at the Hyatt Regency O'Hare in Chicago USA, a great location with excellent weather in May of 2011.
- Three full days of technical and Commercial papers.
- Technical Poster Boards
- An open evening where attendees can take full advantage of the splendid sights, entertainment, dining and tourist attractions of the magnificent city of Chicago.
- Opportunity to meet with leaders from major research companies, suppliers, end users and peers for networking and discussion.
- Three days of wonderful meals, camaraderie and conversation.
- All papers considered for publication in *Finer Points Magazine*.
- Complimentary CD of proceedings to all attendees ... And much more!

## INTERTECH Administrative Details

### NO SMOKING PLEASE

Smoking is prohibited in all meeting facilities.

### CLIMATE FOR CHICAGO IN MAY

Average High Temperature: 71.3°F (21.83°C)

Average Low Temperature: 50.9 °F (10.5°C)

Record High Temperature 98°F (36.7°C)

Record Low Temperature 27°F (-2.8°C)

Average Precipitation: 3.5"

Evenings in May are cool and could require a light jacket or sweater.

### CONFERENCE DRESS

Recommended dress for the conference attendees is business casual. Gentlemen presenters are asked to wear a jacket and ladies suitable business attire. Rooms are air conditioned, so a sweater or a jacket is recommended.

### SPECIAL ASSISTANCE

Prior to the meeting, please call or email IDA Headquarters (Tel: 614-797-2265, email: tkaneida@insight.rr.com) if any special assistance is required for any attendee. On-site, guests requiring special assistance should contact a member of the INTERTECH 2011 staff at the Conference Desk.

### SESSION RECORDINGS & PHOTOGRAPHY

Due to proprietary information and as a courtesy to our speakers, no audio and video recording or photography of the presentations may be made without the prior written permission of the Industrial Diamond Association of America (IDA). All **INTERTECH 2011** presentations are copyrighted to the Industrial Diamond Association of America and the IDA reserves the right to prohibit the recording of presentations or photography even if it is intended for personal use.

MORNING

AFTERNOON

MORNING

AFTERNOON

Evening

MORNING

AFTERNOON

Evening

# INTERTECH 2011\* Event Snapshot

Chicago, Illinois, USA • May 2-4, 2011

## MONDAY, MAY 2

REGISTRATION 8-12:00 Noon  
CONTINENTAL BREAKFAST 7:00-8:00 am

8:00-8:45 am – Keynote Speaker: **Dr. Dean Ho**, Associate Professor Biomedical and Mechanical Engineering Northwestern University, USA

8:45-12 Noon CONCURRENT TECHNICAL SESSIONS	8:45-12 Noon CONCURRENT TECHNICAL SESSIONS
● RESEARCH & DEVELOPMENT	● STONE/CONCRETE

12 Noon - 1:00 pm LUNCH

1:00 - 1:45 pm – Keynote Speaker: **Mark Schweizer**  
CEO & President – Diamond Innovations, USA

1:45 pm - 4:45 pm CONCURRENT TECHNICAL SESSIONS	1:45 pm - 4:45 pm CONCURRENT TECHNICAL SESSIONS
● RESEARCH & DEVELOPMENT	● MINING & DRILLING

6:00 pm - 8:00 pm  
WELCOME RECEPTION – *Hors d'oeuvres & Cocktails*

## TUESDAY, MAY 3

REGISTRATION 8-12:00 Noon  
CONTINENTAL BREAKFAST 7:00-8:00 am

8:00-8:45 am – Keynote Speaker: **Walter Hühn**, Executive Director Advanced Materials and Technologies Division Element Six, Germany

8:45-12 Noon CONCURRENT TECHNICAL SESSIONS	8:45-12 Noon CONCURRENT TECHNICAL SESSIONS	8:45-12 Noon EDUCATIONAL SESSIONS
● ULTRA HARD & DEVELOPMENT MATERIALS	● AEROSPACE	● Superabrasive History ● Abrasive Types & Properties ● Diamond & cBN Grinding

12 Noon - 1:00 pm LUNCH

1:00 pm - 4:45 pm CONCURRENT TECHNICAL SESSIONS	1:00 pm - 4:45 pm CONCURRENT TECHNICAL SESSIONS	1:00 pm - 4:45 pm CONCURRENT EDUCATIONAL SESSIONS
● ULTRA HARD & DEVELOPMENT MATERIALS	● AEROSPACE	● Superabrasive Machining & Drilling PCD & PCBN ● Abrasive Types & Properties ● Non Abrasive Uses

5:30 pm - 10:30 pm  
**OPTIONAL CHICAGO "DINE AROUND" TOUR**  
A Progressive Dining Experience and Tour of Chicago

## WEDNESDAY, MAY 4

REGISTRATION 8-12:00 Noon  
CONTINENTAL BREAKFAST 7:00-8:00 am

8:00-8:45 am – Keynote Speaker: **Mitsuhiro "Chip" Goto**, Managing Director, General Manager – Sumitomo Electric Hardmetal Corporation, Japan

8:45-12 Noon CONCURRENT TECHNICAL SESSIONS	8:45-12 Noon CONCURRENT TECHNICAL SESSIONS	8:45-12 Noon CONCURRENT TECHNICAL SESSIONS
● AUTOMOTIVE	● TOOL PROCESSING & PROPERTIES	● ELECTRONICS & OPTICS

12 Noon - 1:00 pm LUNCH

1:00 pm - 4:45 pm CONCURRENT TECHNICAL SESSIONS	1:00 pm - 4:45 pm CONCURRENT TECHNICAL SESSIONS	1:00 pm - 4:45 pm CONCURRENT TECHNICAL SESSIONS
● AUTOMOTIVE	● TOOL PROCESSING & PROPERTIES	● ELECTRONICS & OPTICS

OPEN EVENING  
**\*PROGRAM SUBJECT TO CHANGE**  
*Depending on final approval of selected Abstracts & Papers*